

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|--|---|---------------------|
| 1 | 607 | (356/614-624,3.01-3.09,3.1-3.12 250/559.38).ccls. and (semiconductor or wafer) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/14 09:46 |
| 2 | 85 | (356/614-624,3.01-3.09,3.1-3.12 250/559.38).ccls. and (semiconductor or wafer) and (line near4 beam) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/14 09:46 |
| 3 | 10 | (356/614-624,3.01-3.09,3.1-3.12 250/559.38).ccls. and (semiconductor or wafer) and (line near4 beam) and (field near3 view) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/11/14 10:25 |
| 4 | 1 | 5969820.pn. | USPAT | 2003/11/14 10:26 |
| 5 | 2 | 5969820.URPN. | USPAT | 2003/11/14 10:33 |